



ESD



TVS



MOS



LDO



Diode



Sensor



DC-DC

Product Specification

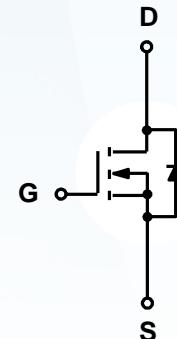
▶ Domestic Part Number	IRFB3207Z
▶ Overseas Part Number	IRFB3207Z
▶ Equivalent Part Number	IRFB3207Z



EV is the abbreviation of name EVVO

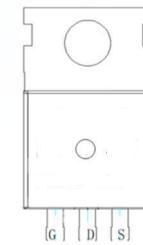
Features

- 80V,150A
 $R_{DS\ ON} < 3.0\text{m}\Omega$ @ $V_{GS}=10\text{V}$ TYP: $2.5\text{m}\Omega$
 $R_{DS\ ON} < 4.0\text{m}\Omega$ @ $V_{GS}=6\text{V}$ TYP: $3.5\text{m}\Omega$
- Surface-mounted package
- Split Gate Trench Technology



Applications

- Power appliances
- BMS appliances
- High power inverter system



Marking and pin assignment

ABSOLUTE MAXIMUM RATINGS ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	80	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ($T_C = 25^\circ\text{C}$) ^(2,3)	I_D	150	A
Pulsed Drain Current ^(1,2,3)	I_{DM}	240	A
Single Pulsed Avalanche Energy ($V_{DD} = 50\text{V}, L = 0.1\text{mH}$) ⁽²⁾	E_{AS}	420	mJ
Drain Power Dissipation	P_D	156	W
Thermal Resistance from Junction to Case ⁽²⁾	$R_{\theta JC}$	0.8	$^\circ\text{C}/\text{W}$
Thermal Resistance- Junction to Ambient ⁽²⁾	$R_{\theta JA}$	62.5	$^\circ\text{C}/\text{W}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55~+150	$^\circ\text{C}$

Notes:

1. Pulse width $\leq 300\ \mu\text{s}$, duty cycle $\leq 2\ %$
2. Surface Mounted on n 1 in² pad area, t $\leq 10\ \text{sec.}$
3. Limited by bonding wire

MOSFET ELECTRICAL CHARACTERISTICS($T_J=25^\circ\text{C}$ unless otherwise noted)

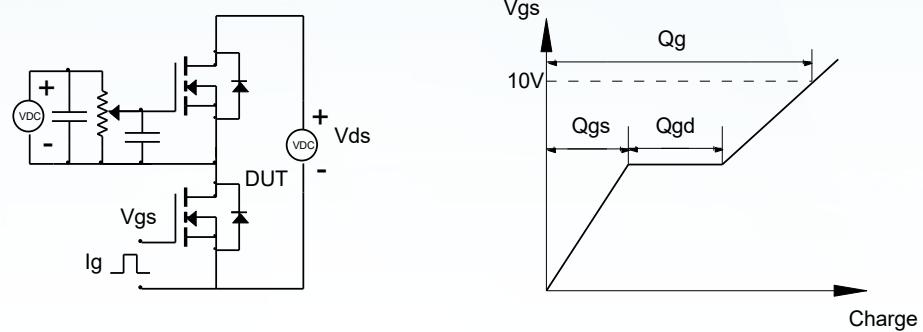
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	80	-	-	V
Zero gate voltage drain current	I_{DSS}	$V_{\text{DS}} = 64\text{V}, V_{\text{GS}} = 0\text{V}$	-	-	1	μA
Gate-body leakage current	I_{GSS}	$V_{\text{GS}} = \pm 20\text{V}, V_{\text{DS}} = 0\text{V}$	-	-	± 100	nA
Gate threshold voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	2.0	-	4.0	V
Drain-source on-resistance ^(a)	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 30\text{A}$	-	2.5	3.0	$\text{m}\Omega$
		$V_{\text{GS}} = 6\text{V}, I_D = 20\text{A}$		3.5	4.0	$\text{m}\Omega$
Dynamic characteristics						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 40\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0\text{MHz}$	-	5591	-	pF
Output Capacitance	C_{oss}		-	744	-	
Reverse Transfer Capacitance	C_{rss}		-	75	-	
Switching characteristics						
Turn-on delay time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 40\text{V}, I_D = 30\text{A}, R_G = 4.5\Omega, R_L = 1.3\Omega, V_G = 10\text{V}$	-	23	-	ns
Turn-on rise time	t_r		-	65	-	
Turn-off delay time	$t_{\text{d}(\text{off})}$		-	71	-	
Turn-off fall time	t_f		-	73	-	
Total Gate Charge	Q_g	$V_{\text{DS}} = 40\text{V}, I_D = 30\text{A}, V_{\text{GS}} = 10\text{V}$	-	101	-	nC
Gate-Source Charge	Q_{gs}		-	28	-	
Gate-Drain Charge	Q_{gd}		-	25	-	
Source-Drain Diode characteristics						
Diode Forward voltage ^(a)	V_{SD}	$T_J = 25^\circ\text{C}, V_{\text{GS}} = 0\text{V}, I_s = 30\text{A}$	-	-	1.3	V
Diode Forward current	I_s	$T_c = 25^\circ\text{C}$	-	-	150	A
Body Diode Reverse Recovery Time	trr	$T_J = 25^\circ\text{C}, IF = 30\text{A}, di/dt = 100\text{A}/\mu\text{s}$		62		ns
Body Diode Reverse Recovery Charge	Q_{rr}	$T_J = 25^\circ\text{C}, IF = 30\text{A}, di/dt = 100\text{A}/\mu\text{s}$		83		uc

Notes:

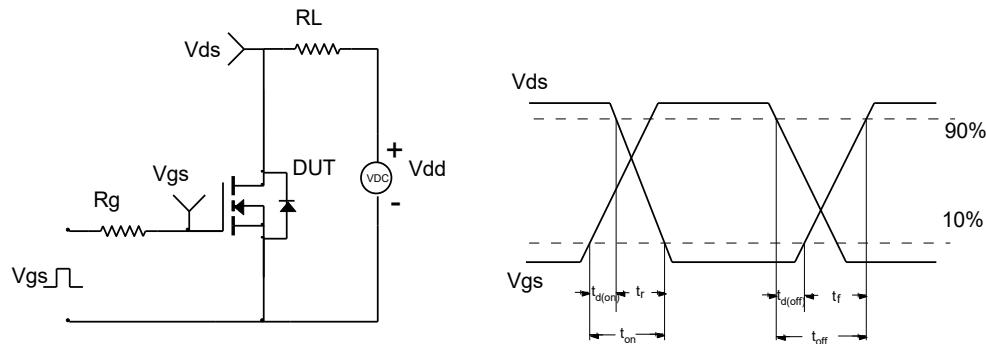
- a) Pulse width $\leq 300\ \mu\text{s}$, duty cycle $\leq 2\%$
- b) Guaranteed by design, not subject to production testing

Test Circuit

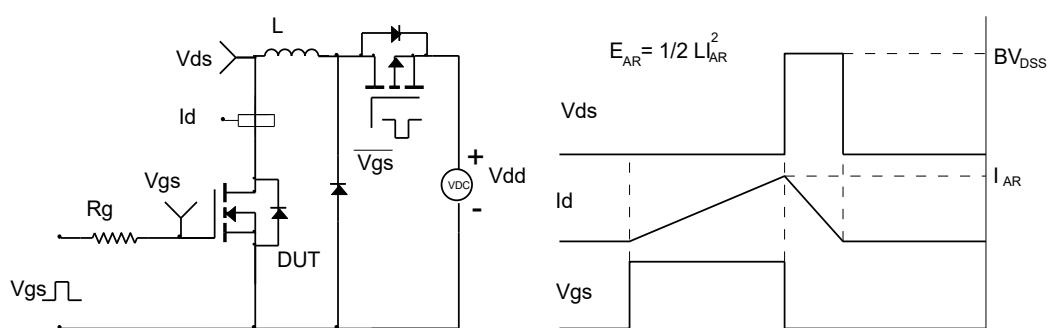
Gate Charge Test Circuit & Waveform



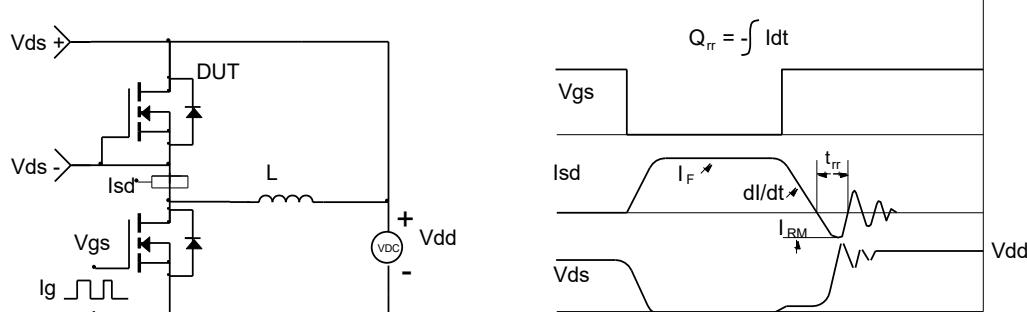
Resistive Switching Test Circuit & Waveforms



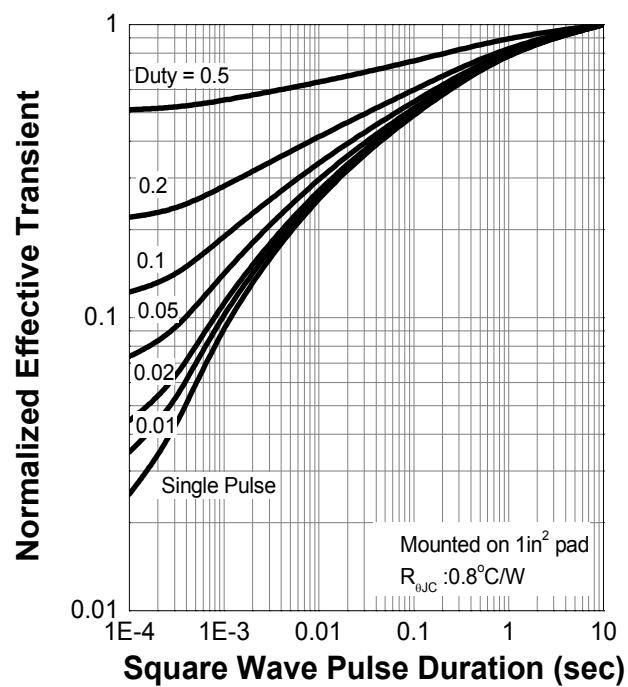
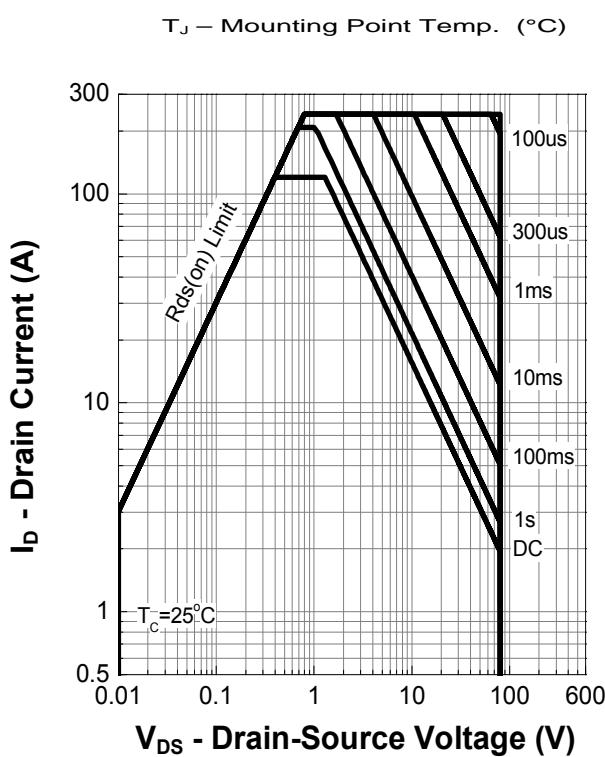
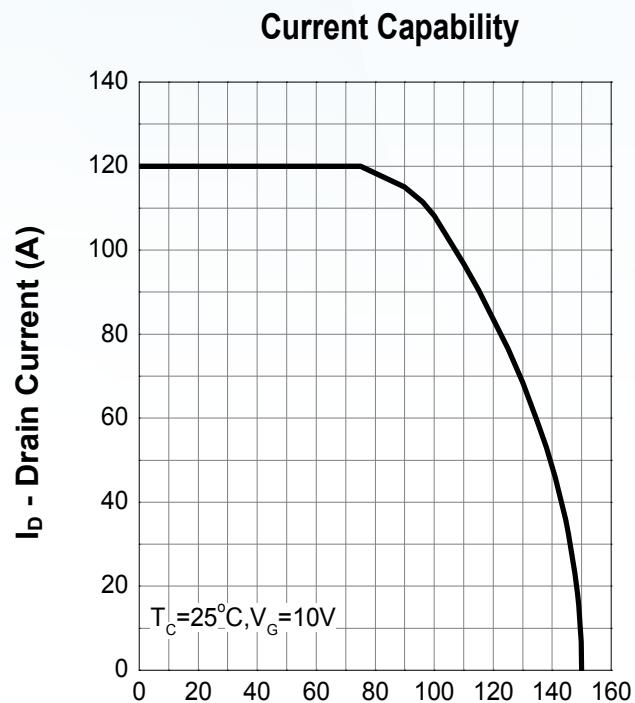
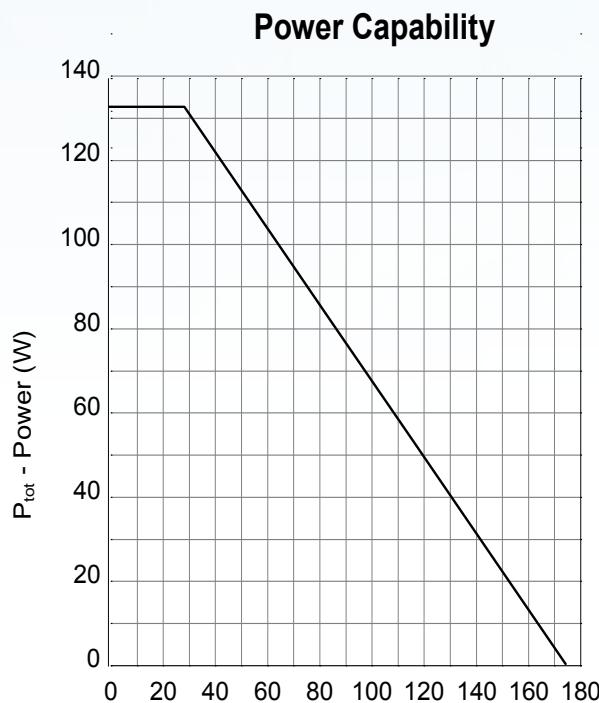
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



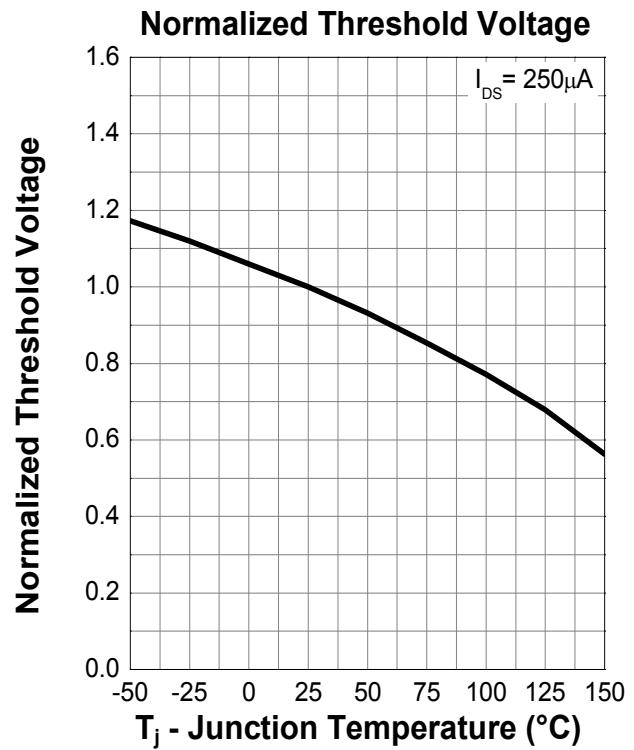
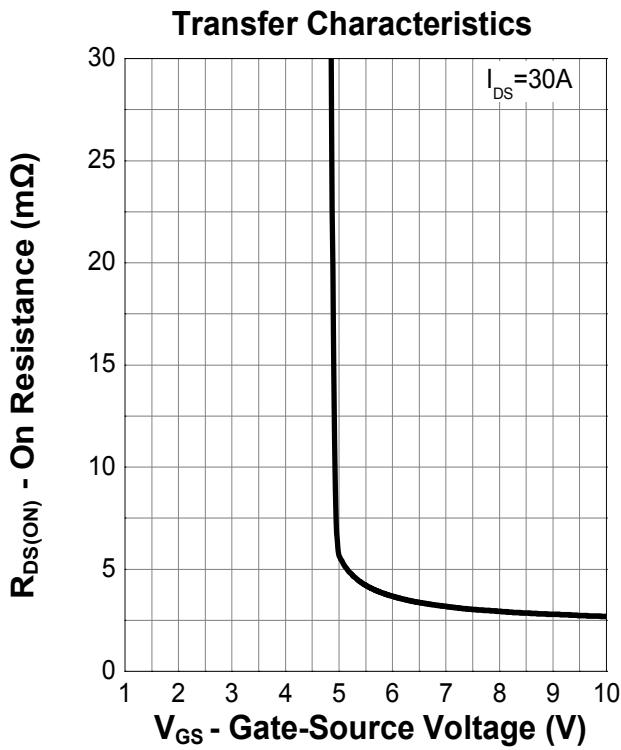
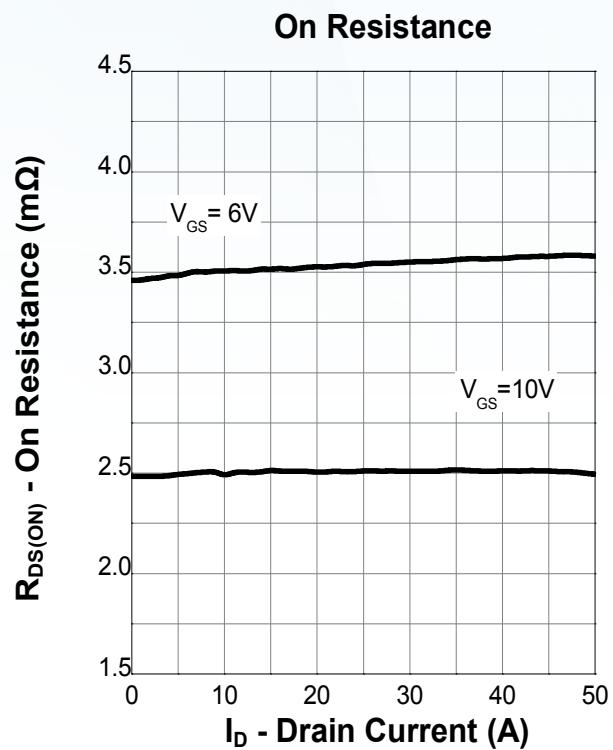
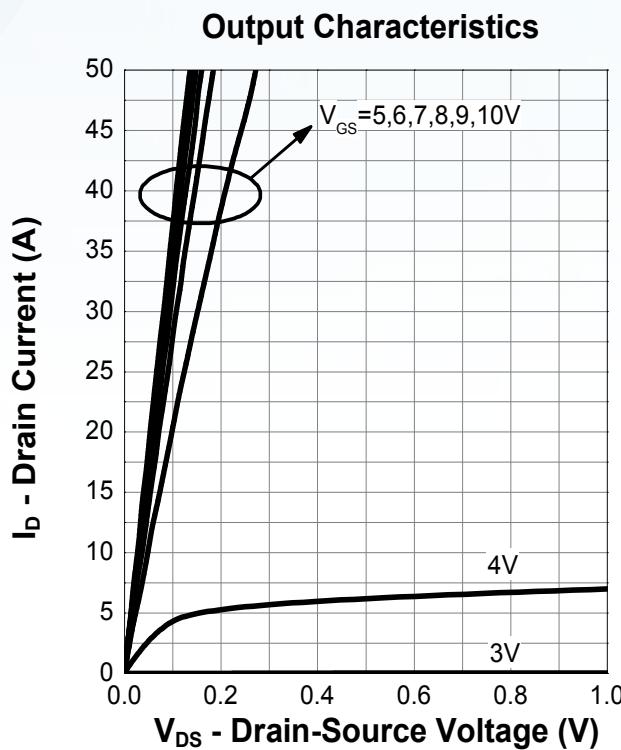
Diode Recovery Test Circuit & Waveforms



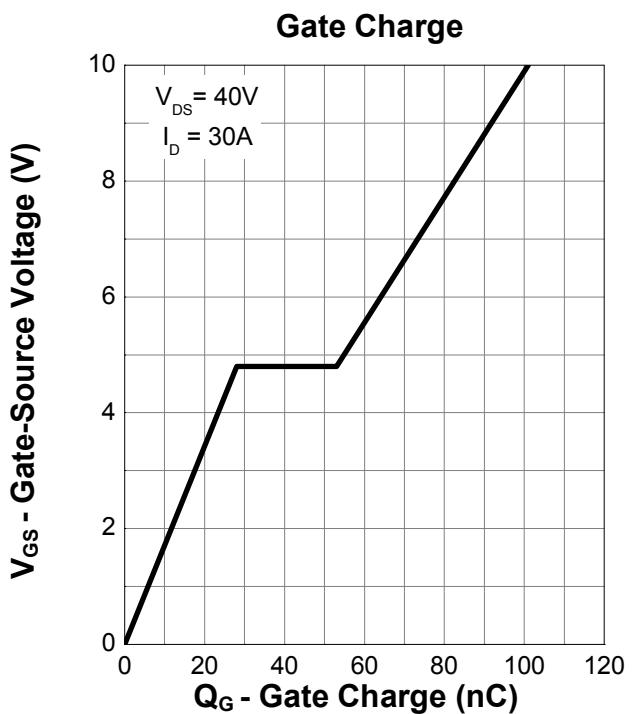
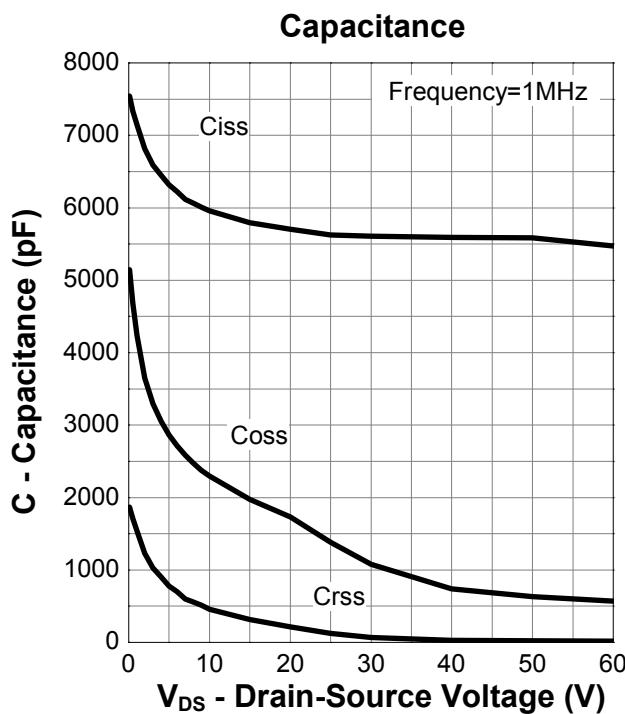
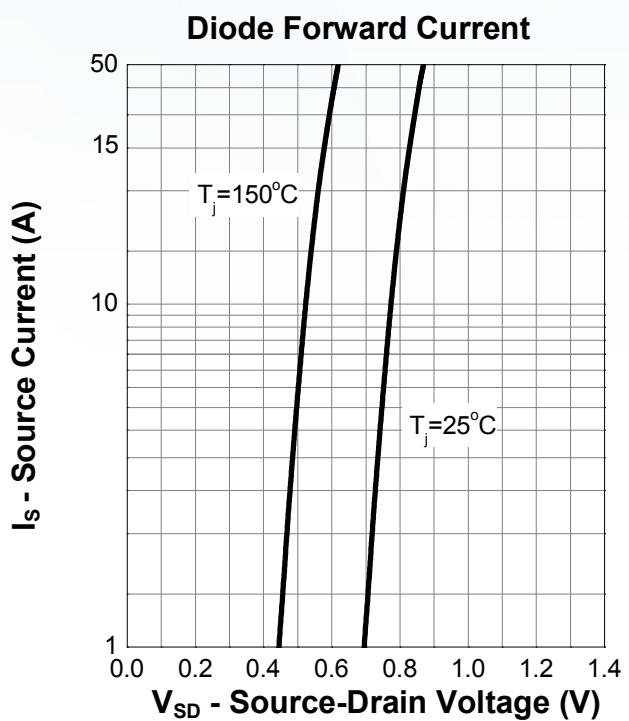
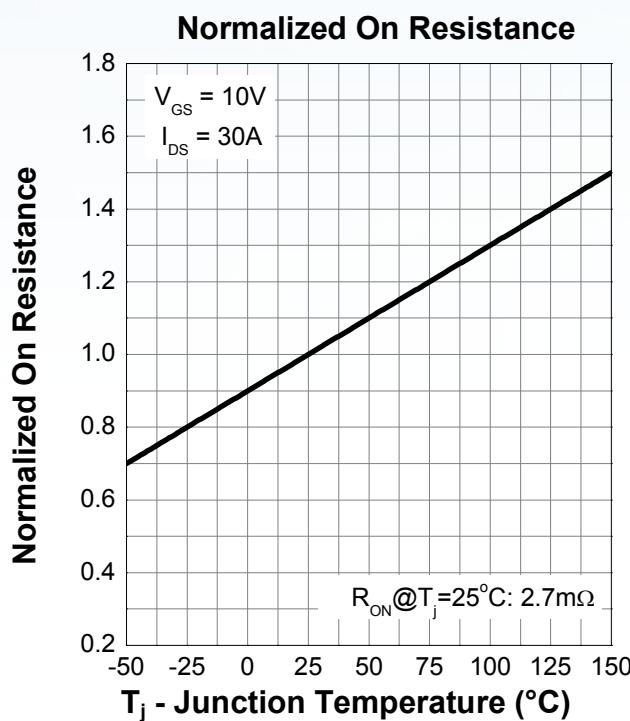
Typical Characteristics (cont.)



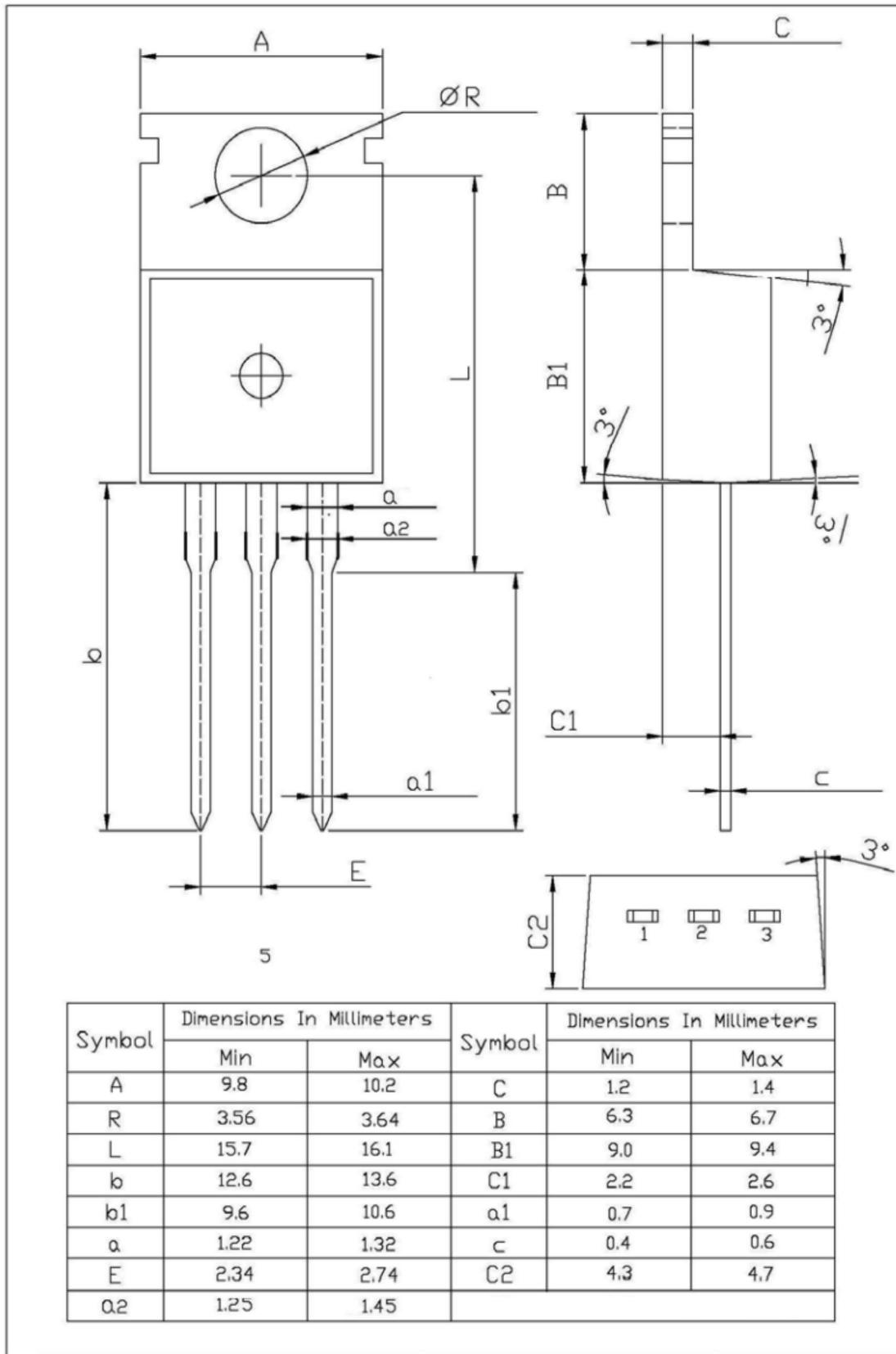
Typical Characteristics (cont.)



Typical Characteristics (cont.)



TO-220 Package Dimensions



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